



Device Material Content

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Package: 484 caBGA
Total Device Weight 0.8935 Grams

Package Code:

BBG484

Products:

XO4D

Assembly: ASEK

Size (mm): 19 x 19

Lead pitch (mm): 0.8

MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.740%	0.0155	1.740%	0.0155	Silicon chip	7440-21-3	100.00%	
Mold Compound	55.789%	0.4985	41.842% 8.089% 2.789% 2.789% 0.279%	0.3739 0.0723 0.0249 0.0249 0.0025	Aluminum oxide Silica Epoxy resin Phenol Resin Carbon Black	1344-28-1 60676-86-0 - - 1333-86-4	75.00% 14.50% 5.00% 5.00% 0.50%	Mold Compound: Kyocera KE-G1250AHT
D/A Epoxy	0.620%	0.00554	0.534% 0.037% 0.031% 0.006% 0.012% 0.001%	0.00477 0.00033 0.00027 0.00006 0.00010 0.00001	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol Perfluoropolyoxalkane ether 2-[[[2,2 bis[[[(1-oxoallyloxy)methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl diacrylate bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 925918-64-5 94108-97-1 15520-11-3	86.09% 5.92% 4.92% 1.00% 1.88% 0.19%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	0.360%	0.0032	0.348% 0.011% 0.001%	0.0031 0.00010 0.00001	Copper (Cu) Palladium (Pd) Gold (Au)	7440-50-8 7440-05-3 7440-57-5	96.55% 3.10% 0.35%	Au coated PCC, 0.02mm dia
Solder Balls	15.140%	0.1353	14.610% 0.454% 0.076%	0.1305 0.0041 0.0007	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate Core	8.432%	0.0753	1.747% 0.953% 0.953% 0.953% 0.688% 3.139%	0.0156 0.0085 0.0085 0.0085 0.0061 0.0280	Continuous Filament Fiber Glass Bismaleimide Triazine Cyanic acid (1-methylethylidene)di-4,1-phenylene ester homopolymer Other Resin Aluminum Hydroxide Copper	65997-17-3 105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-50-8	20.72% 11.30% 11.30% 11.30% 8.16% 37.22%	BT Resin CCL-HL832NX-A 2 layer
Solder mask	7.380%	0.0659	4.044% 1.417% 1.417% 0.325% 0.037% 0.037% 0.103%	0.0361 0.0127 0.0127 0.0029 0.0003 0.0003 0.0009	Plastic: PAK Plastic: EP Barium sulphate Talc (Magnesium silicate) Inorganic Ingredient, TS Colorant, TS Additives, TS	- - 7727-43-7 14807-96-6 - - -	54.80% 19.20% 19.20% 4.40% 0.50% 0.50% 1.40%	Solder mask PSR4000 AUS 320 Cured
Foil	10.540%	0.0942	8.643% 1.590% 0.307%	0.0772 0.0142 0.0027	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	82.000% 15.090% 2.910%	
	100.000%	0.8935	100.000%	0.8935				

Note:

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